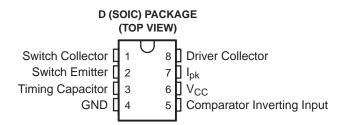


SLLS654B-APRIL 2005-REVISED SEPTEMBER 2008

# **1.5-A PEAK BOOST/BUCK/INVERTING SWITCHING REGULATOR**

# **FEATURES**

- Qualified for Automotive Applications
- Wide Input Voltage Range...3 V to 40 V
- High Output Switch Current...Up to 1.5 A
- Adjustable Output Voltage
- Oscillator Frequency...Up to 100 kHz
- Precision Internal Reference...2%
- Short-Circuit Current Limiting
- Low Standby Current



# **DESCRIPTION/ORDERING INFORMATION**

The MC33063A is an easy-to-use IC containing all the primary circuitry needed for building simple dc-dc converters. The device primarily consists of an internal temperature-compensated reference, a comparator, an oscillator, a PWM controller with active current limiting, a driver, and a high-current output switch. Thus, the device requires minimal external components to build converters in the boost, buck, and inverting topologies.

The MC33063A is characterized for operation from -40°C to 125°C.

## **ORDERING INFORMATION**<sup>(1)</sup>

T <sub>A</sub>	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 125°C	SOIC – D	Reel of 2500	MC33063AQDRQ1	33063AQ	

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

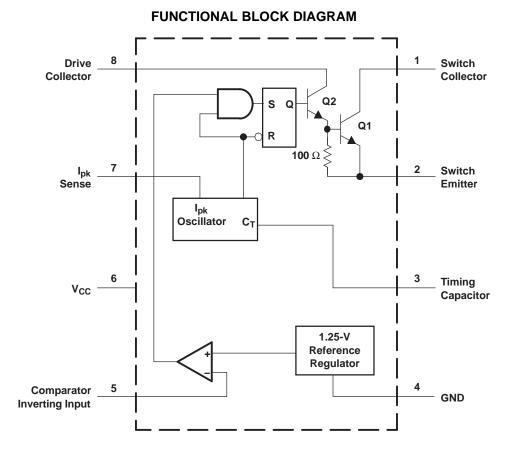


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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INSTRUMENTS

**EXAS** 



# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

V <sub>CC</sub>	Supply voltage	40 V	
V <sub>IR</sub>	Comparator Inverting Input voltage range		–0.3 V to 40 V
V <sub>C(switch)</sub>	Switch Collector voltage		40 V
V <sub>E(switch)</sub>	Switch Emitter voltage	V <sub>PIN1</sub> = 40 V	40 V
V <sub>CE(switch)</sub>	Switch Collector to Switch Emitter voltage		40 V
V <sub>C(driver)</sub>	Driver Collector voltage		40 V
I <sub>C(driver)</sub>	Driver Collector current		100 mA
I <sub>SW</sub>	Switch current		1.5 A
$\theta_{JA}$	Package thermal impedance <sup>(2)(3)</sup>		97°C/W
TJ	Operating virtual junction temperature		150°C
T <sub>stg</sub>	Storage temperature range		–65°C to 150°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.

# **Recommended Operating Conditions**

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	3	40	V
T <sub>A</sub>	Operating free-air temperature	-40	125	°C



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# **Electrical Characteristics**

 $V_{CC}$  = 5 V,  $T_A$  = full operating range (unless otherwise noted) (see block diagram)

### Oscillator

	PARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	UNIT
f <sub>osc</sub>	Oscillator frequency	$V_{PIN5} = 0 V, C_T = 1 nF$	25°C	24	33	42	kHz
I <sub>chg</sub>	Charge current	$V_{CC} = 5 V \text{ to } 40 V$	25°C	24	35	42	μA
I <sub>dischg</sub>	Discharge current	$V_{CC} = 5 V \text{ to } 40 V$	25°C	140	220	260	μA
I <sub>dischg</sub> /I <sub>chg</sub>	Discharge-to-charge current ratio	$V_{PIN7} = V_{CC}$	25°C	5.2	6.5	7.5	
V <sub>lpk</sub>	Current-limit sense voltage	$I_{dischg} = I_{chg}$	25°C	250	300	350	mV

# **Output Switch**<sup>(1)</sup>

	PARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	UNIT
V <sub>CE(sat)</sub>	Saturation voltage – Darlington connection	$I_{SW}$ = 1 A, pins 1 and 8 connected	Full range		1	1.3	V
V <sub>CE(sat)</sub>	Saturation voltage – non-Darlington connection <sup>(2)</sup>	$I_{SW} = 1 \text{ A, } R_{PIN8} = 82 \Omega \text{ to } V_{CC},$ Forced $\beta \sim 20$	Full range		0.45	0.7	V
h <sub>FE</sub>	DC current gain	$I_{SW} = 1 \text{ A}, V_{CE} = 5 \text{ V}$	25°C	50	75		
I <sub>C(off)</sub>	Collector off-state current	V <sub>CE</sub> = 40 V	Full range		0.01	100	μΑ

(1) Low duty-cycle pulse testing is used to maintain junction temperature as close to ambient temperature as possible.

(2) In the non-Darlington configuration, if the output switch is driven into hard saturation at low switch currents (≤300 mA) and high driver currents (≥30 mA), it may take up to 2 µs for the switch to come out of saturation. This condition effectively shortens the off time at frequencies ≥30 kHz, becoming magnified as temperature increases. The following output drive condition is recommended in the non-Darlington configuration:

Forced  $\beta$  of output switch =  $I_{C,SW} / (I_{C,driver} - 7 \text{ mA}) \ge 10$ , where  $\sim 7 \text{ mA}$  is required by the 100- $\Omega$  resistor in the emitter of the driver to forward bias the V<sub>be</sub> of the switch.

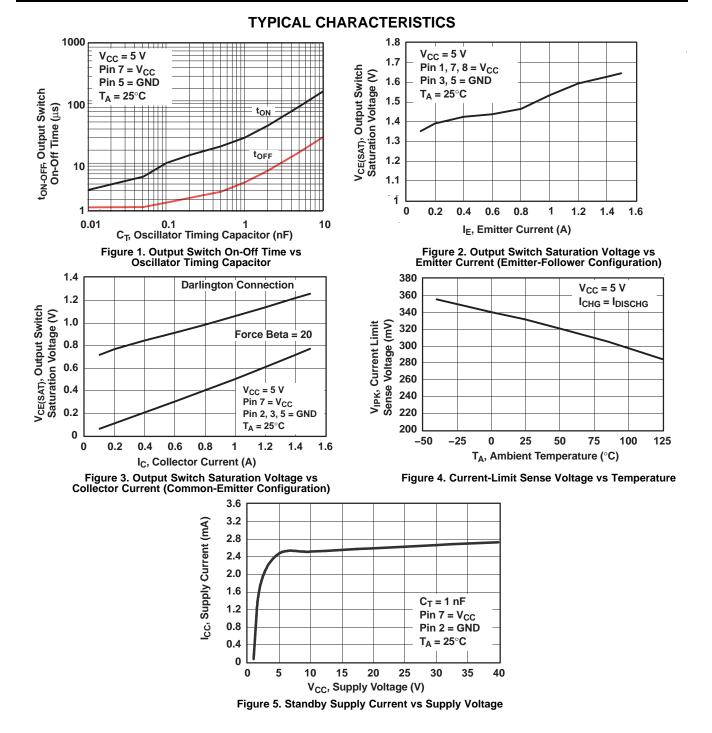
# Comparator

	PARAMETER	TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	UNIT
V	Threshold voltage		25°C	1.225	1.25	1.275	V
V <sub>th</sub>	Threshold voltage		Full range	1.21		1.29	v
$\Delta V_{th}$	Threshold-voltage line regulation	$V_{CC} = 5 V \text{ to } 40 V$	Full range		1.4	5	mV
I <sub>IB</sub>	Input bias current	$V_{IN} = 0 V$	Full range		-20	-400	nA

## **Total Device**

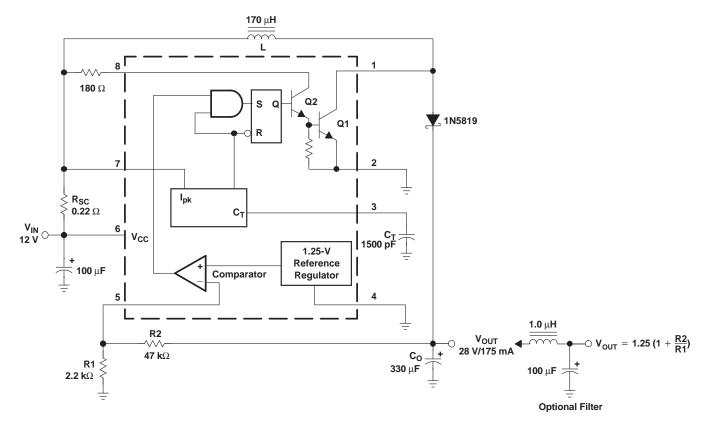
	PARAMETER	TEST CONDITIONS	TA	MIN	MAX	UNIT
I <sub>CC</sub>	Supply current		Full range		4	mA







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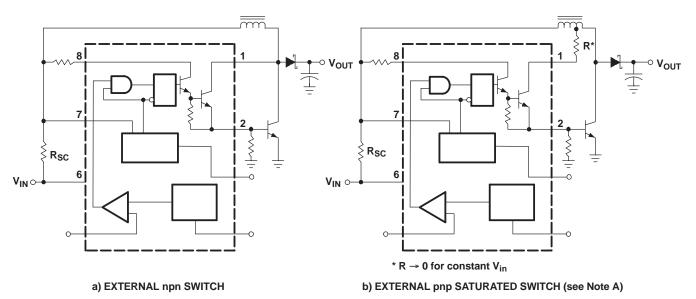


# **TYPICAL CHARACTERISTICS (continued)**

Figure 6. Step-Up Converter

TEST	CONDITIONS	RESULTS
Line regulation	$V_{IN} = 8 V$ to 16 V, $I_{O} = 175 \text{ mA}$	30 mV ± 0.05%
Load regulation	$V_{IN} = 12 \text{ V}, I_{O} = 75 \text{ mA to } 175 \text{ mA}$	10 mV ± 0.017%
Output ripple	$V_{IN} = 12 \text{ V}, I_{O} = 175 \text{ mA}$	400 mV <sub>PP</sub>
Efficiency	V <sub>IN</sub> = 12 V, I <sub>O</sub> = 175 mA	87.7%
Output ripple with optional filter	V <sub>IN</sub> = 12 V, I <sub>O</sub> = 175 mA	40 mV <sub>PP</sub>

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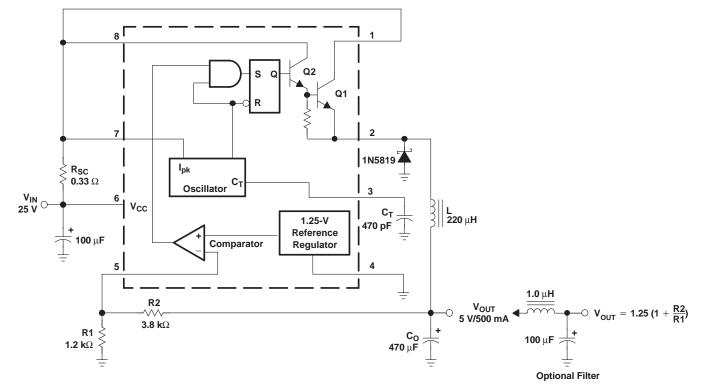


A. If the output switch is driven into hard saturation (non-Darlington configuration) at low switch currents (≤300 mA) and high driver currents (≥30 mA), it may take up to 2 µs to come out of saturation. This condition will shorten the off time at frequencies ≥30 kHz and is magnified at high temperatures. This condition does not occur with a Darlington configuration because the output switch cannot saturate. If a non-Darlington configuration is used, the output drive configuration in Figure 7b is recommended.

Figure 7. External Current-Boost Connections for I<sub>C</sub> Peak Greater Than 1.5 A



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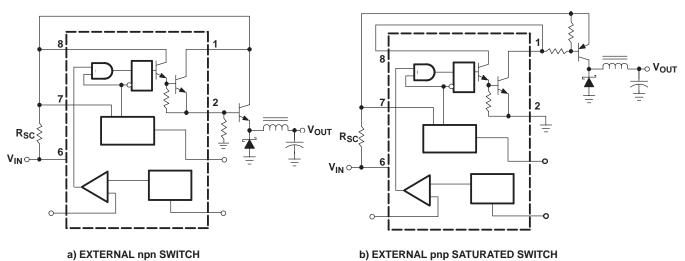
## Figure 8. Step-Down Converter

TEST	CONDITIONS	RESULTS
Line regulation	$V_{IN}$ = 15 V to 25 V, $I_O$ = 500 mA	12 mV ± 0.12%
Load regulation	$V_{IN} = 25 \text{ V}, I_{O} = 50 \text{ mA to } 500 \text{ mA}$	3 mV ± 0.03%
Output ripple	$V_{IN} = 25 \text{ V}, I_O = 500 \text{ mA}$	120 mV <sub>PP</sub>
Short-circuit current	$V_{IN} = 25 \text{ V}, \text{ R}_{L} = 0.1 \Omega$	1.1 A
Efficiency	V <sub>IN</sub> = 25 V, I <sub>O</sub> = 500 mA	83.7%
Output ripple with optional filter	V <sub>IN</sub> = 25 V, I <sub>O</sub> = 500 mA	40 mV <sub>PP</sub>

Product Folder Link(s): MC33063A-Q1



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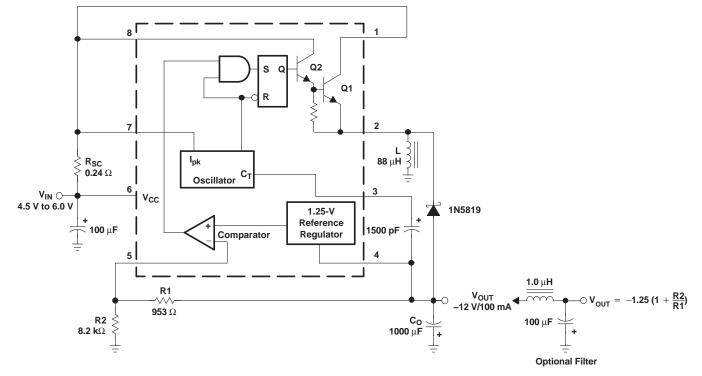


ERNAL INFI SWITCH

# Figure 9. External Current-Boost Connections for $\rm I_{C}$ Peak Greater Than 1.5 A



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# Figure 10. Voltage-Inverting Converter

TEST	CONDITIONS	RESULTS
Line regulation	$V_{IN} = 4.5 \text{ V to } 6 \text{ V}, I_{O} = 100 \text{ mA}$	3 mV ± 0.12%
Load regulation	$V_{IN} = 5 \text{ V}, I_O = 10 \text{ mA} \text{ to } 100 \text{ mA}$	0.022 V ± 0.09%
Output ripple	V <sub>IN</sub> = 5 V, I <sub>O</sub> = 100 mA	500 mV <sub>PP</sub>
Short-circuit current	$V_{IN} = 5 V, R_L = 0.1 \Omega$	910 mA
Efficiency	V <sub>IN</sub> = 5 V, I <sub>O</sub> = 100 mA	62.2%
Output ripple with optional filter	V <sub>IN</sub> = 5 V, I <sub>O</sub> = 100 mA	70 mV <sub>PP</sub>



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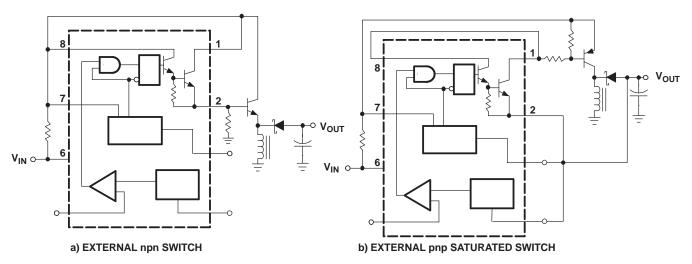


Figure 11. External Current-Boost Connections for  $I_C$  Peak Greater Than 1.5 A



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# APPLICATION INFORMATION

CALCULATION	STEP UP	STEP DOWN	VOLTAGE INVERTING
$t_{on}/t_{off}$	$\frac{V_{out} + V_F - V_{in(min)}}{V_{in(min)} - V_{sat}}$	$\frac{V_{out} + V_F}{V_{in(min)} - V_{sat} - V_{out}}$	$\frac{ V_{out}  + V_F}{V_{in} - V_{sat}}$
$(t_{on} + t_{off})$	$\frac{1}{f}$	$\frac{1}{f}$	$\frac{1}{f}$
t <sub>off</sub>	$\frac{t_{on} + t_{off}}{\frac{t_{on}}{t_{off}} + 1}$	$\frac{t_{on} + t_{off}}{\frac{t_{on}}{t_{off}} + 1}$	$\frac{t_{on} + t_{off}}{\frac{t_{on}}{t_{off}} + 1}$
t <sub>on</sub>	$\left( t_{on} \ + \ t_{off}  ight) - \ t_{off}$	$\left( t_{on} \ + \ t_{off}  ight) - \ t_{off}$	$\left( t_{on} \ + \ t_{off}  ight) - \ t_{off}$
CT	$4 imes 10^{-5}t_{on}$	$4 imes 10^{-5}t_{on}$	$4 imes10^{-5}t_{on}$
I <sub>pk(switch)</sub>	$2I_{out(max)}\left(\frac{t_{on}}{t_{off}} + 1\right)$	2I <sub>out(max)</sub>	$2I_{out(max)}\left(\frac{t_{on}}{t_{off}} + 1\right)$
R <sub>SC</sub>	0.3 I <sub>pk(switch)</sub>	0.3 Ipk(switch)	0.3 I <sub>pk(switch)</sub>
L <sub>(min)</sub>	$\left(\frac{\left(V_{in(min)}-V_{sat}\right)}{I_{pk(switch)}}\right)\!t_{on(max)}$	$\left(\frac{\left(V_{in(min)}-V_{sat}-V_{out}\right)}{I_{pk(switch)}}\right)\!t_{on(max)}$	${\left(\frac{\left(V_{in(min)}-V_{sat}\right)}{I_{pk(switch)}}\right)} t_{on(max)}$
Co	9 <mark>I<sub>out</sub>t<sub>on</sub> V<sub>ripple(pp)</sub></mark>	$\frac{I_{pk(switch)}(t_{on} + t_{off})}{8V_{ripple(pp)}}$	9 $rac{I_{out}t_{on}}{V_{ripple(pp)}}$



# PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins F	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
MC33063AQDRQ1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF MC33063A-Q1 :

Catalog: MC33063A

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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